PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6277975

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DEOKKYUNG YANG	03/13/2017
YONGMIN KIM	03/13/2017
JAEHYUK CHOI	03/13/2017
YEOCHAN KO	03/13/2017
HEESOO LEE	03/13/2017

RECEIVING PARTY DATA

Name:	STATS CHIPPAC PTE. LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17008918

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 480-499-9400
Email: main@plgaz.com
Correspondent Name: PATENT LAW GROUP: ATKINS AND ASSOCIATES
Address Line 1: 123 W. CHANDLER HEIGHTS ROAD, #12535
Address Line 4: CHANDLER, ARIZONA 85248

ATTORNEY DOCKET NUMBER:	2515.0496 CON2
NAME OF SUBMITTER:	LISA ROSSETTI
SIGNATURE:	/Lisa Rossetti/
DATE SIGNED:	09/01/2020

Total Attachments: 5
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, DEOKKYUNG YANG of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SYSTEM-IN-PACKAGE WITH DOUBLE SIDED MOLDING, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0496, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

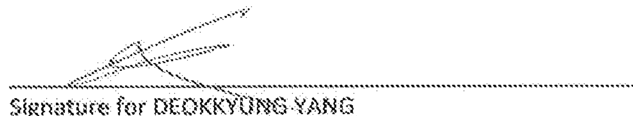
I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

2017. 03. 13
Date Signed


Signature for DEOKKYUNG YANG

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YONGMIN KIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SYSTEM-IN-PACKAGE WITH DOUBLE SIDED MOLDING, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0496, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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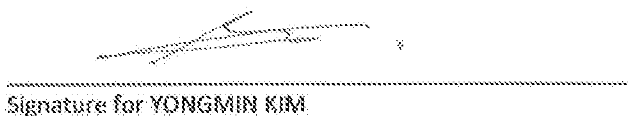

2019, 03, 13

Date Signed

Signature for YONGMIN KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JAEHYUK CHOI of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SYSTEM-IN-PACKAGE WITH DOUBLE SIDED MOLDING, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0496, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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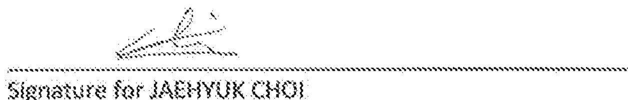
2019. 03. 13

Date Signed



Signature for JAEHYUK CHOI

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, YEOCHAN KO of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SYSTEM-IN-PACKAGE WITH DOUBLE SIDED MOLDING, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0496, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2017 . 03 . 13	Ko
Date Signed	Signature for YEOCHAN KO

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEESOO LEE of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 10 Ang Mo Kio Street 65, Techpoint #04-08/09, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SYSTEM-IN-PACKAGE WITH DOUBLE SIDED MOLDING, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0496, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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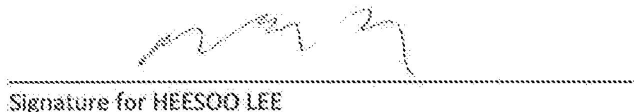
2019 .03 .13

Date Signed



Signature for HEESOO LEE